

Dual 1-of-4 Decoder / Demultiplexer in bare die form

Rev 1.0 16/04/18

Description

The 74HC139 is fabricated using a 2.5µm 5V CMOS process and has the same high speed performance of LSTTL combined with CMOS low power consumption. This device consists of x2 independent 1–of–4 decoders, each decoding a 2 bit address to 1–of–4 active–low outputs. Active–low Selects facilitate the demultiplexing and cascading functions. The demultiplexing function is executed by using the Address inputs to select the desired device output and utilizing the Select as a data input.

Features:

Output Drive Capability: 10 LSTTL Loads

■ Low Input Current: 1µA

Outputs directly interface CMOS, NMOS and TTL

Operating Voltage Range: 2V to 6V

CMOS High Noise Immunity

Function compatible with 74LS139.

Ordering Information

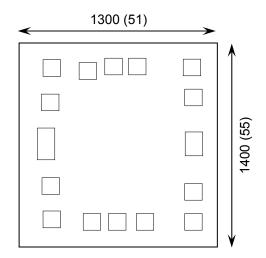
The following part suffixes apply:

No suffix - MIL-STD-883 /2010B Visual Inspection

For High Reliability versions of this product please see

54HC139

Die Dimensions in µm (mils)



Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 350µm(14 Mils) On request
- Assembled into Ceramic Package On request

Mechanical Specification

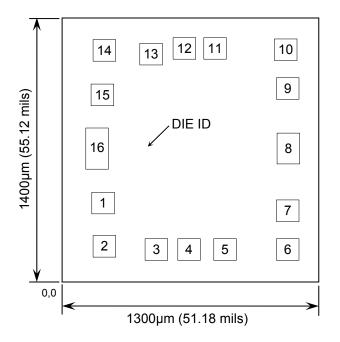
Die Size (Unsawn)	1300 x 1400 51 x 55	µm mils	
Minimum Bond Pad Size	106 x 106 4.17 x 4.17	µm mils	
Die Thickness	350 (±20) 13.78 (±0.79)	μm mils	
Top Metal Composition	Al 1%Si 1.1μ	m	
Back Metal Composition	N/A – Bare Si		



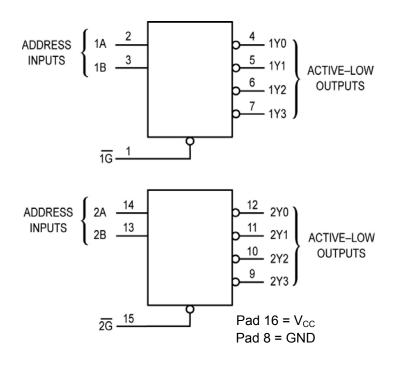


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Pad Layout and Functions



Logic Diagram



PAD	FUNCTION	COORDINATES (mm)			
FAD	1 0140 11014	X	Y		
1	1G	0.152	0.366		
2	1A	0.162	0.132		
3	1B	0.422	0.122		
4	1Y0	0.59	0.122		
5	1Y1	0.772	0.122		
6	1Y2	1.088	0.122		
7	1Y3	1.088	0.333		
8	GND	1.088	0.619		
9	2Y3	1.088	0.972		
10	2Y2	1.078	1.173		
11	2Y1	0.722	1.183		
12	2Y0	0.566	1.183		
13	2B	0.396	1.153		
14	2A	0.162	1.173		
15	2G	0.152	0.938		
16	V _{CC}	0.122	0.591		
CON	NECT CHIP BA	CK TO V _{CC} C	R FLOAT		

Truth Table

IN	PUTS			OUT	PUTS	
G	1A	1B	Y0	Y1	Y2	Y3
Н	Χ	Χ	Н	Н	Н	I
L	L	L	L	Н	Н	Н
L	L	Н	Н	L	Н	Н
L	Н	L	Н	Н	L	Н
L	Н	Н	Н	Н	Н	L

X = don't care





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Absolute Maximum Ratings¹

PARAMETER	SYMBOL	VALUE	UNIT
DC Supply Voltage (Referenced to GND)	V _{CC}	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V _{IN}	-1.5 to V _{CC} +1.5	V
DC Output Voltage (Referenced to GND)	V _{OUT}	-0.5 to V _{CC} +0.5	V
DC Input Current, per pin	I _{IN}	±20	mA
DC Output Current, per pin	I _{OUT}	±25	mA
DC V _{CC} or GND Current, per pin	I _{CC}	±50	mA
Power Dissipation in Still Air ²	P _D	750	mW
Storage Temperature Range	T _{STG}	-65 to 150	°C

^{1.} Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability. 2. Measured in plastic DIP package, results in die form are dependent on die attach and assembly method.

Recommended Operating Conditions³ (Voltages referenced to GND)

PARAMETER	SYMBOL	MIN	MAX	UNITS	
DC Supply Voltage		V _{CC}	2	6	V
DC Input or Output Voltage		V_{IN} , V_{OUT}	0	V _{CC}	V
Operating Temperature Range		TJ	0	+85	°C
	V _{CC} = 2.0V		0	1000	
Input Rise and Fall Time	V _{CC} = 4.5V	t _r , t _f	0	500	ns
	$V_{CC} = 6.0V$		0	400	

^{3.} This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range GND \leq (V_{IN} or V_{OUT}) \leq V_{CC} . Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC Electrical Characteristics (Voltages Referenced to GND)

PARAMETER	SYMBOL	SYMBOL V _{cc} CONDITIONS		UNITS			
			CONDITIONS	25°C	85°C	FULL RANGE⁴	OMITO
Minimum High-Level Input Voltage		2.0V	V _{OUT} = 0.1V or	1.5	1.5	1.5	
	V _{IH}	4.5V	V_{CC} -0.1V $ I_{OUT} \le 20\mu A$	3.15	3.15	3.15	V
		6.0V		4.2	4.2	4.2	
Maximum Low-Level Input Voltage	V _{IL} 2.0V 4.5V 6.0V	2.0V	$V_{OUT} = 0.1V$ or	0.5	0.5	0.5	
		4.5V	V _{CC} -0.1V	1.35	1.35	1.35	V
		6.0V I _{OUT} ≤ 20μA	1.8	1.8	1.8		

^{4.} $0^{\circ}C \le T_{J} \le +85^{\circ}C$





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DC Electrical Characteristics (Voltages Referenced to GND)

PARAMETER	SYMBOL	V _{cc}	CONDITIONS		UNITS		
		₩00	CONDITIONS	25°C	85°C	FULL RANGE⁴	Oitiio
Minimum High-Level Output Voltage		2.0V	1.9	1.9	1.9		
		4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT} \le 20 \mu A$	4.4	4.4	4.4	
	.,	6.0V	1.0011 = = 0	5.9	5.9	5.9	.,
	V _{OH}	4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left I_{OUT} \right \le 4.0 \text{mA}$	3.98	3.84	3.84	V
		$\begin{array}{ c c c c }\hline 6.0V & V_{IN} = V_{IH} \text{ or } V_{IL} \\ & I_{OUT} \leq 5.2\text{mA} \end{array}$	5.48	5.34	5.34		
	V _{OL} 2.0V 4.5V 6.0V 4.5V 6.0V	2.0V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left I_{OUT} \right \le 20 \mu A$	0.1	0.1	0.1	
		4.5V		0.1	0.1	0.1	
Maximum Low-Level		6.0V		0.1	0.1	0.1	
Output Voltage		4.5V	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $\left I_{OUT} \right \le 4.0 \text{mA}$	0.26	0.33	0.33	V
		$\begin{array}{ c c c }\hline & V_{IN} = V_{IH} \text{ or } V_{IL} \\ & & I_{OUT} \le 5.2\text{mA} \end{array}$	0.26	0.33	0.33		
Maximum Input Leakage Current	I _{IN}	6.0V	V _{IN} = V _{CC} or GND	±0.1	±1.0	±1.0	μA
Maximum Quiescent Supply Current	I _{CC}	6.0V	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0\mu A$	4	40	40	μA

AC Electrical Characteristics⁵

PARAMETER	SYMBOL	V _{cc} CONDITIONS		LIMITS			
17tto tille 1 Ett			CONDITIONS	25°C	85°C	FULL RANGE ⁴	UNITS
Maximum		2.0V		115	145	145	
Propagation Delay, Select to Output Y	t _{PLH,} t _{PHL}	4.5V	$C_L = 50pF,$ $t_r = t_f = 6ns$	23	29	29	ns
(Figure 1, 3)		6.0V		20	25	25	
Maximum	t _{PLH} , t _{PHL}	2.0V	$C_L = 50 \text{pF},$ $t_r = t_f = 6 \text{ns}$	115	145	145	
Propagation Delay, Input A to Output Y		4.5V		23	29	29	ns
(Figure 2,3)		6.0V		20	25	25	
Maximum Output		2.0V	0 50 5	75	95	95	
Transition Time, Any Output	t _{TLH} , t _{THL}	4.5V	$C_L = 50pF,$ $t_r = t_f = 6ns$	15	19	19	ns
(Figure 1,3)	6.0V		13	16	16		
Maximum Input Capacitance	C _{IN}	-	-	10	10	10	pF
Power Dissipation			T _J = 25°C,		TYPI	CAL	
Capacitance (Per Decoder) ⁷	C _{PD}	-	$V_{CC} = 5.0V$		5	5	pF

^{6.} Not production tested in die form, characterized by chip design and tested in package.



^{7.} Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.



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Pad Description

ADDRESS INPUTS

1A, 1B, 2A, 2B

(Pads 2, 3, 14, 13)

When the respective 1-of-4 decoder is enabled these inputs determine which of its four active-low outputs is selected.

CONTROL INPUTS

1G, 2G

(Pads 1, 15)

Active—low select inputs. For a low level on this input, the outputs for that particular decoder follow the Address inputs. A high level on this input forces all outputs to a high level.

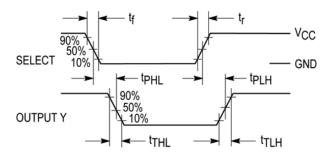
OUTPUTS

1Y0, 1Y1, 1Y2, 1Y3, 2Y0, 2Y1, 2Y2, 2Y3

(Pads 4-7, 12, 11, 10, 9)

Active—low outputs. These outputs assume a low level when addressed and the appropriate Select input is active. These outputs remain high when not addressed or the appropriate Select input is inactive.

Switching Waveforms



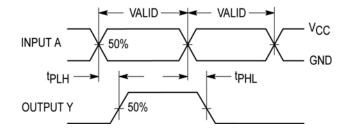
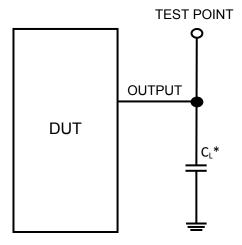


Figure 1

Figure 2

Test Circuit



^{*} Includes all probe and jig capacitance





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